



Form Type	Distribute	Version	2.0	Ref	IPC 1752A	Sectionals	Material Info	Subsectionals	D, A
Supplier Information									
Company Name	TE Connectivity	Request Document ID		Contact Name	Rebecca Dong	Contact Title	Product Compliance Engineer		
Company Unique ID	TE Connectivity	Response Date	2015-12-10	Contact Email	Rebecca_dong@te.com				
Contact Phone Number	86(21)33259330								
Legal Statement									
Supplier Acceptance	true								
Legal Statement									
The information provided in this document is based upon reasonable inquiry of our suppliers. This information is subject to change. This information does not in any way modify existing purchase specifications or existing contractual or other agreements terms between TE Connectivity (or its affiliated companies) and its customers.									
Product									
Manufacturer Item number	1-1337481-0	Amount	2447.71	Version	-	Identity			
Manufacturer Item Name	SMB R/A PCB Skt 50Ohm Gold Plt	Weight Uom	mg	Mfr Site		Authority			
Date		UOM	Each						
EUroHS-0508	Product(s) meets EU RoHS requirements by application of the selected exemption(s)								
ChinaRoHS-0508	Product(s) is NOT eligible for marking with the e code under China's Measures for Administration of the control of pollution by Electronic Information Products								
EUREACH-1214	REACH Candidate Substances of Very High Concern ARE NOT Contained in the Product Above the Limits per the Definition within REACH								
Product Disclosure									
Sub-Item/Material/Substance	Level	Name	Substance Category	Substance CAS	Substance Concentration	Quantity	Mass per Unit	UOM	Exemption
Material	1	Body-nickel plating				1.0	5.86	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.99	1.0	5.85941	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.01	1.0	5.86E-4	mg	
Material	1	Body-Cu plating				1.0	4.0	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.01	1.0	4.0E-4	mg	
Substance	2	Copper	Supplier	7440-50-8	99.99	1.0	3.9996	mg	
Material	1	Contact-nickel plating				1.0	0.5	mg	
Substance	2	Nickel	Nickel	7440-02-0	99.99	1.0	0.49995	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.01	1.0	5.0E-5	mg	
Material	1	Contact-Cu plating				1.0	0.33	mg	
Substance	2	Copper	Supplier	7440-50-8	99.99	1.0	0.32997	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.01	1.0	3.3E-5	mg	
Material	1	Contact				1.0	87.2	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.72	1.0	0.62784	mg	
Substance	2	Zinc	Supplier	7440-66-6	36.98	1.0	32.24656	mg	
Substance	2	Copper	Supplier	7440-50-8	59.8	1.0	52.1456	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	2.5	1.0	2.18	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Material	1	Body				1.0	2229.0	mg	
Substance	2	Zinc	Supplier	7440-66-6	36.98	1.0	824.2842	mg	
Substance	2	Copper	Supplier	7440-50-8	59.8	1.0	1332.942	mg	

Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.72	1.0	16.0488	mg	
Substance	2	Lead	Lead/Lead Compounds	7439-92-1	2.5	1.0	55.725	mg	6(c) Lead as an alloying element in copper containing up to 4% lead by weight
Material	1	Insulator				1.0	120.0	mg	
Substance	2	Ethene, 1,1,2,2-tetrafluoro-, homopolymer	Supplier	9002-84-0	100.0	1.0	120.0	mg	
Material	1	Contact-gold plating				1.0	0.73	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.01	1.0	7.3E-5	mg	
Substance	2	Gold	Supplier	7440-57-5	99.99	1.0	0.72993	mg	
Material	1	Body-gold plating				1.0	0.09	mg	
Substance	2	Contains No Reportable TE5081-2 Substances	Supplier	TE5081-2-1212	0.01	1.0	1.0E-5	mg	
Substance	2	Gold	Supplier	7440-57-5	99.99	1.0	0.089991	mg	